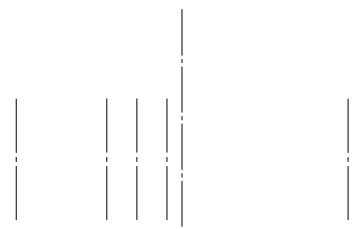
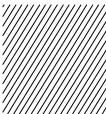


10 9 8 7 6 5 4 3 2 1

No.	PART	MATERIAL
①	HOUSING	耐熱性樹脂 UL94V-0 HEATPROOF RESIN UL94V-0
②	TERMINAL A	銅合金 COPPER ALLOY 錫メッキ : 1.0 micro-meter MIN. TIN
③	TERMINAL B	ニッケルメッキ (下地) : 1.0 micro-meter MIN. NICKEL (UNDER PLATING)
④	NAIL	銅合金 COPPER ALLOY 錫メッキ : 1.0 micro-meter MIN. TIN ニッケルメッキ (下地) : 1.0 micro-meter MIN. NICKEL (UNDER PLATING)



	5.6	5.2				
503148 - 249*						
	5.6	3.2				
503148 - 209*						
	5.6	3.2				
503148 - 169*						
	5.6	2.5				
503148 - 129*						12
503148 - 109*					11.	10
	2.75	3.6				
EMBOSSED TAPE PACKAGE					A	CIRCUIT
オーダー番号 ORDER No.						

REV	DESCRIPTION
10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR ±1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		MM ONLY	4:1	METRIC	
DRAWN BY	DATE	TITLE			
T. HANYU	2007/11/2	1.5 W/B CONN. DUAL R/A REC. ASSY			
CHECKED BY	DATE	molex			
K. ASAKAWA	2007/11/2				
APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
YO. ITO	2007/11/2	SEE CHART	SD-503148-001	1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2